Agilent Technologies, Inc Docket No. 10003772-5 Title: Integrated Circuit Metallization Using A Titanium/Aluminum Alloy Inv. Ricky D. Snyder 3 pp (figs. 1-4)

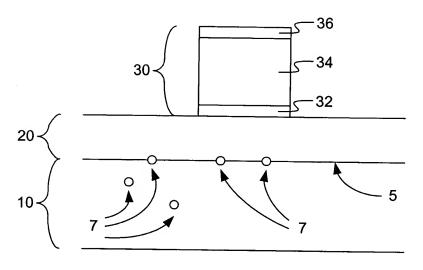


FIG. 1

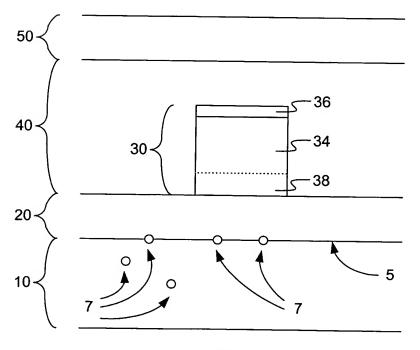


FIG. 2

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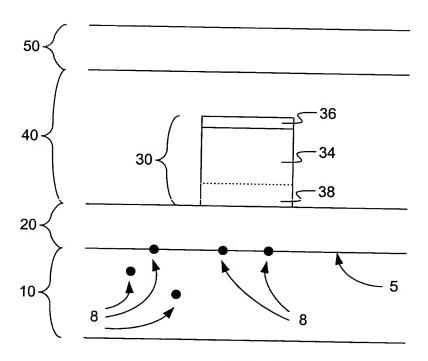


FIG. 3

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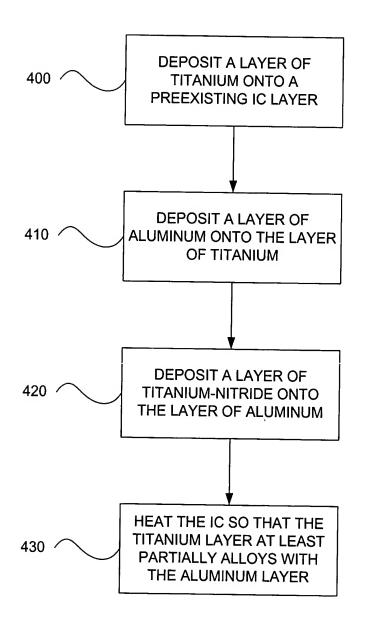


FIG. 4